

FH4504TL

N-Channel Trench Power MOSFET

◆ General Description

The FH4504TL is the N-Channel logic enhancement mode power field effect transistors are produced using high cell density, DMOS trench technology. This high density process is especially tailored to minimize on-state resistance.

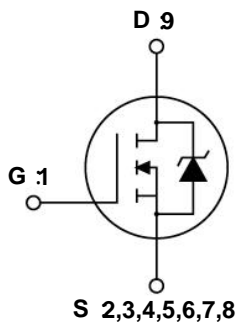
◆ Applications

- High power inverter system
- LCD TV appliances
- Load Switch

◆ Features

Parameter	Typ.	Unit
V_{DS}	40	V
I_D (@ $V_{GS} = 10V$)	250	A
$R_{DS(ON)}$ (@ $V_{GS} = 10V$) (Typ)	1.2	$m\Omega$
$R_{DS(ON)}$ (@ $V_{GS} = 4.5V$) (Typ)	1.9	$m\Omega$

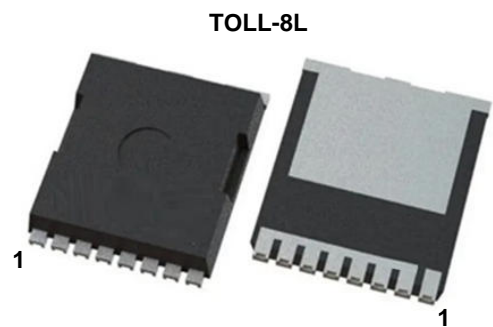
- Surface-mounted package
- Advanced trench cell design
- Super Trench



Schematic diagram



Marking and pin assignment



Top view

Bottom View

Symbol	Parameter	Conditions	Min	Max	Unit
V_{DS}	Drain-Source Voltage	$T_C = 25\text{ }^\circ\text{C}$	40	-	V
V_{GS}	Gate-Source Voltage	$T_C = 25\text{ }^\circ\text{C}$	-	± 20	V
I_D^{***}	Drain Current (DC)	$T_C = 25\text{ }^\circ\text{C}, V_{GS} = 10\text{ V}$	-	250	A
I_{DM}^{****}	Drain Current (Pulsed)	$T_C = 25\text{ }^\circ\text{C}, V_{GS} = 10\text{ V}$	-	1300	A
P_{tot}	Drain power dissipation	$T_C = 25\text{ }^\circ\text{C}$	-	300	W
T_{stg}	Storage Temperature		-55	150	$^\circ\text{C}$
T_J	Junction Temperature		-	150	$^\circ\text{C}$
I_S	Continuous-Source Current	$T_C = 25\text{ }^\circ\text{C}$	-	250	A
E_{AS}	Single Pulsed Avalanche Energy	$V_{DD}=40V, L=1.0mH$	-	1052	mJ
$R_{\theta JA}^{**}$	Thermal Resistance- Junction to Ambient		-	40	$^\circ\text{C/W}$
$R_{\theta JC}^{**}$	Thermal Resistance- Junction to Case		-	0.5	

Notes :

* Surface Mounted on minimum footprint pad area.

** Pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$

*** Maximum current rating is package limited.

Electrical Characteristics (T_A = 25 °C Unless Otherwise Noted)

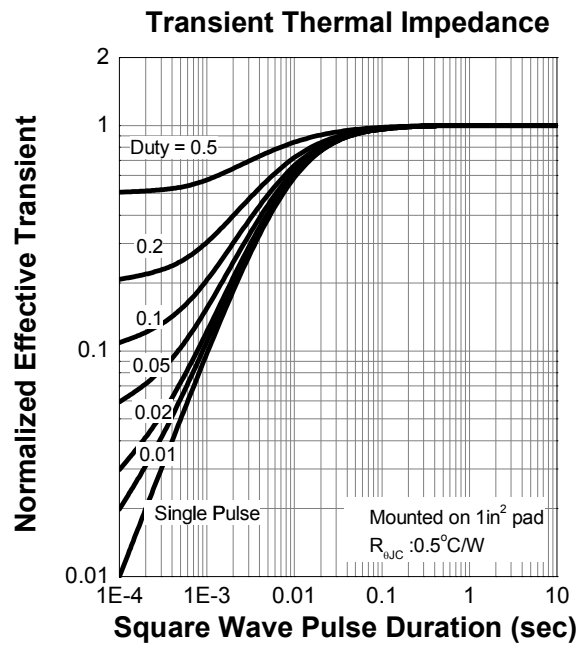
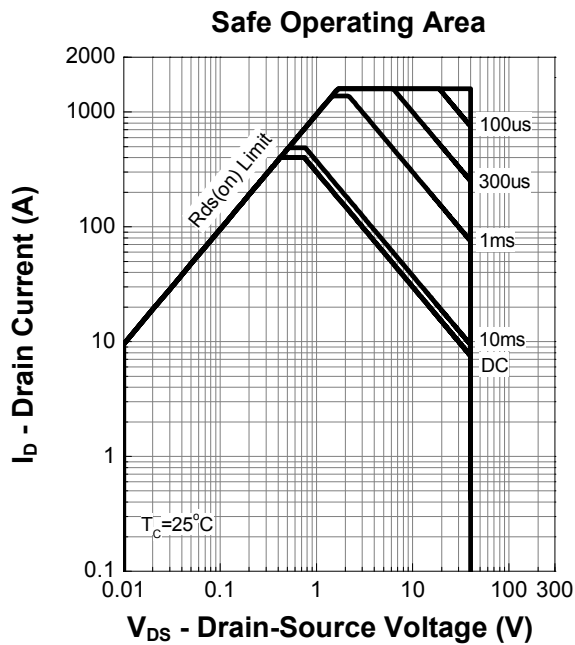
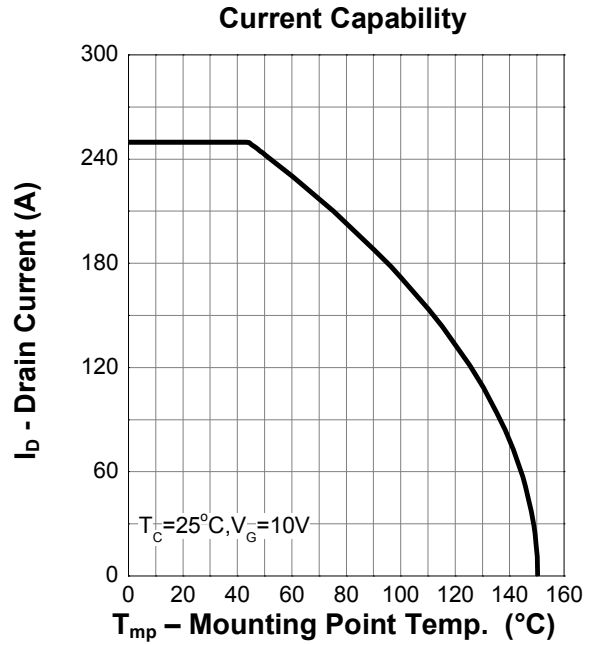
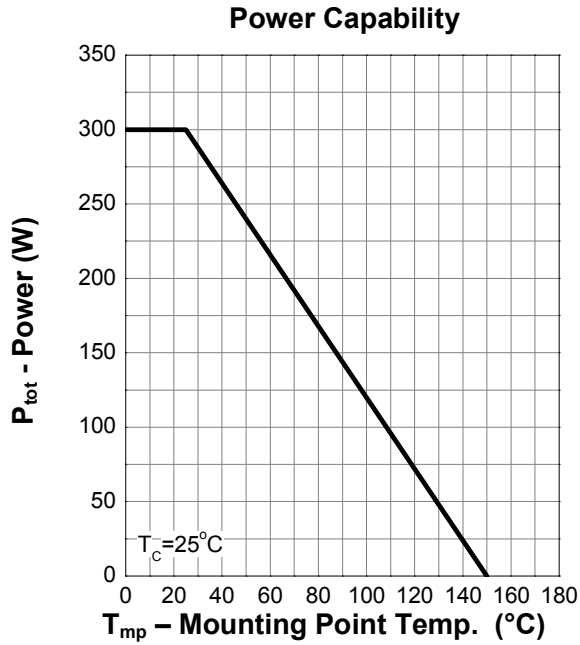
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static Characteristics						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} = 0 V, I _D = 250 μA	40	-	-	V
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _{DS} = 250 μA	1.5	2.0	2.5	V
I _{DSS}	Zero Gate Voltage Source Current	V _{DS} = 32 V, V _{GS} = 0 V	-	-	1	μA
		T _J = 85 °C	-	-	30	μA
I _{GSS}	Gate Leakage Current	V _{GS} = ± 20 V, V _{DS} = 0 V	-	-	± 100	nA
R _{DS(on)} ^a	Drain-Source On-State Resistance	V _{GS} = 10 V, I _D = 20 A	-	1.2	1.5	mΩ
		V _{GS} = 4.5 V, I _D = 10 A	-	1.9	2.5	
Diode Characteristics						
V _{SD} ^a	Diode Forward Voltage	I _{SD} = 20 A, V _{GS} = 0 V	-	-	1.3	V
t _{rr}	Reverse Recovery Time	I _{SD} = 20 A, di _{SD} /dt = 100 A/μs	-	68	-	ns
Q _{rr}	Reverse Recovery Charge		-	92	-	nC
Dynamic Characteristics^b						
C _{iss}	Input Capacitance	V _{GS} = 0 V, V _{DS} = 20 V Frequency = 1 MHz	-	4925	-	pF
C _{oss}	Output Capacitance		-	1655	-	
C _{rss}	Reverse Transfer Capacitance		-	122	-	
t _{d(on)}	Turn-on Delay Time	V _{DS} = 20 V, V _{GEN} = 10 V, R _G = 4.5 Ω, R _L = 1 Ω, I _{DS} = 20 A	-	16	-	ns
t _r	Turn-on Rise Time		-	48	-	
t _{d(off)}	Turn-off Delay Time		-	75	-	
t _f	Turn-off Fall Time		-	42	-	
Gate Charge Characteristics^b						
Q _g	Total Gate Charge	V _{DS} = 20 V, V _{GS} = 10 V, I _{DS} = 20 A	-	81	-	nC
Q _{gs}	Gate-Source Charge		-	18	-	
Q _{gd}	Gate-Drain Charge		-	15	-	

Notes :

a : Pulse test ; pulse width ≤ 300 μs, duty cycle ≤ 2 %

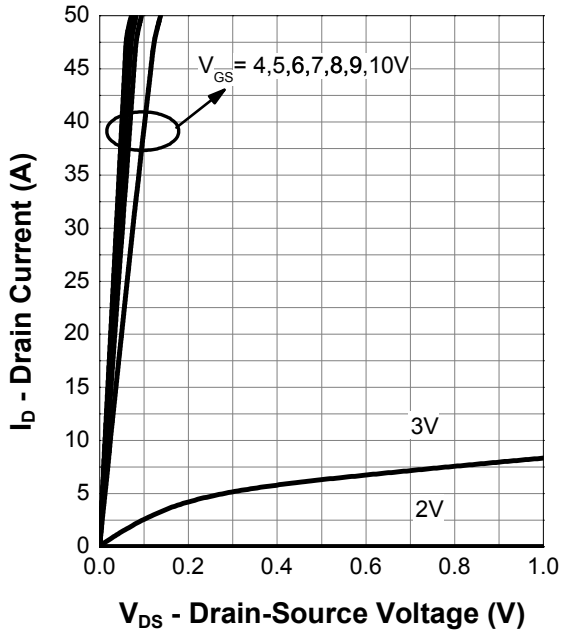
b : Guaranteed by design, not subject to production testing

Typical Characteristics

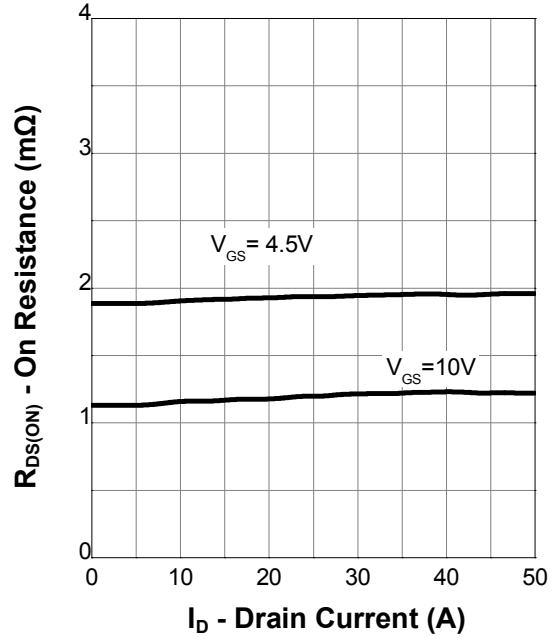


Typical Characteristics (Cont.)

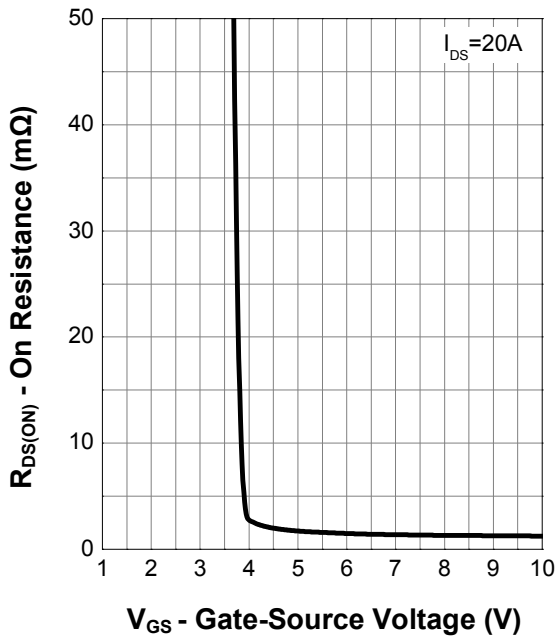
Output Characteristics



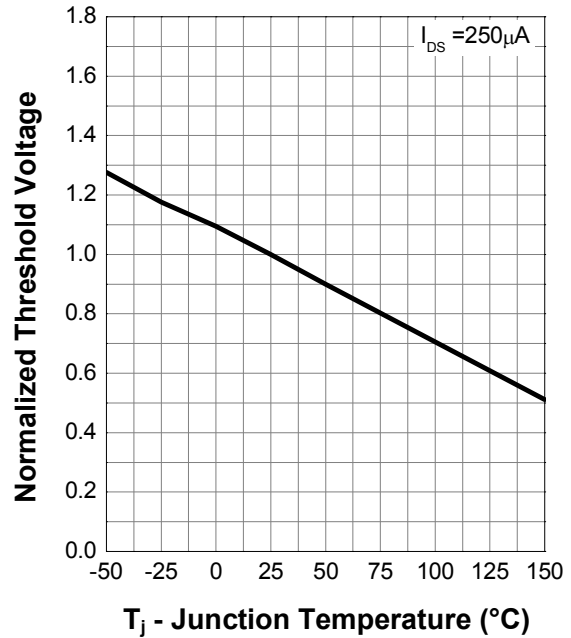
On Resistance



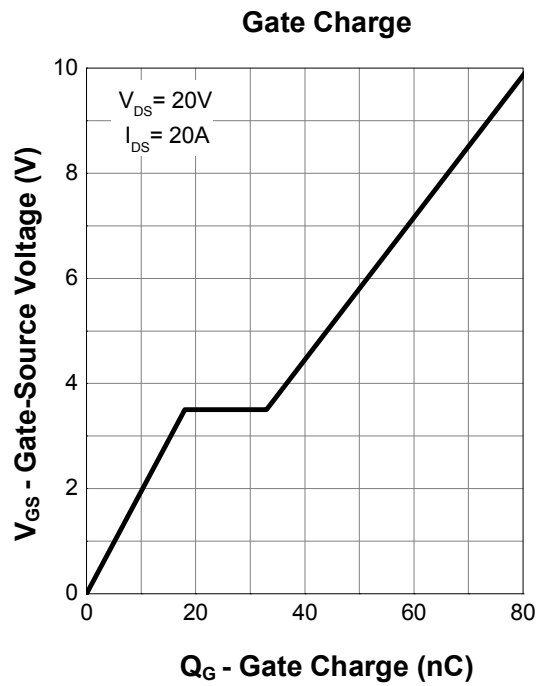
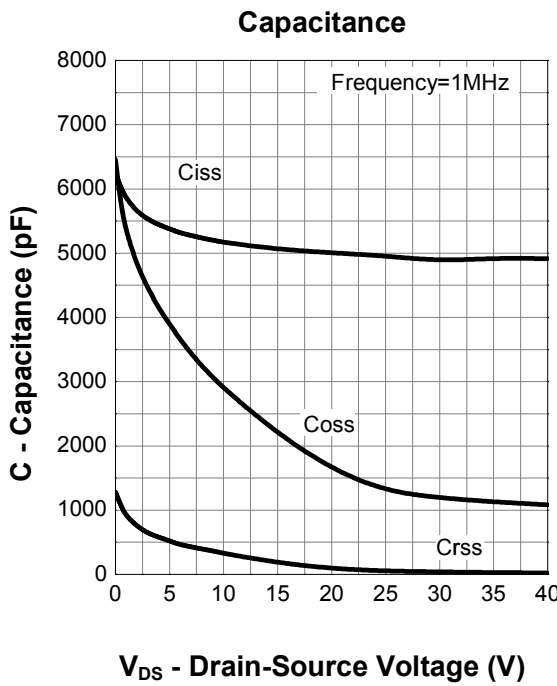
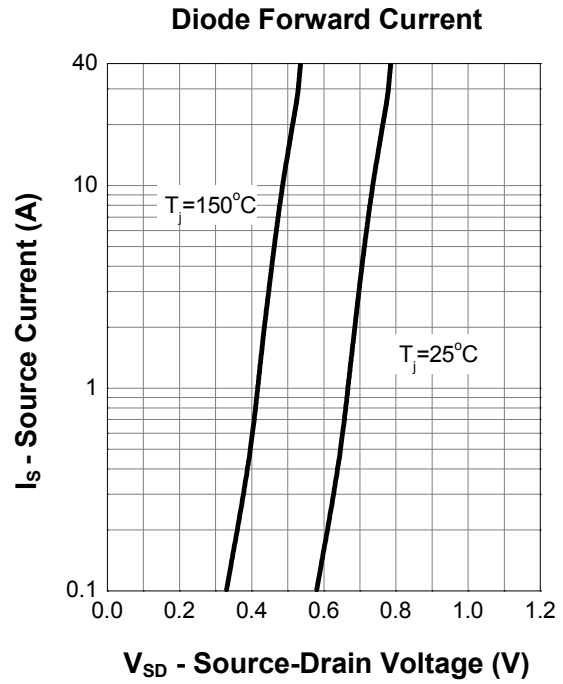
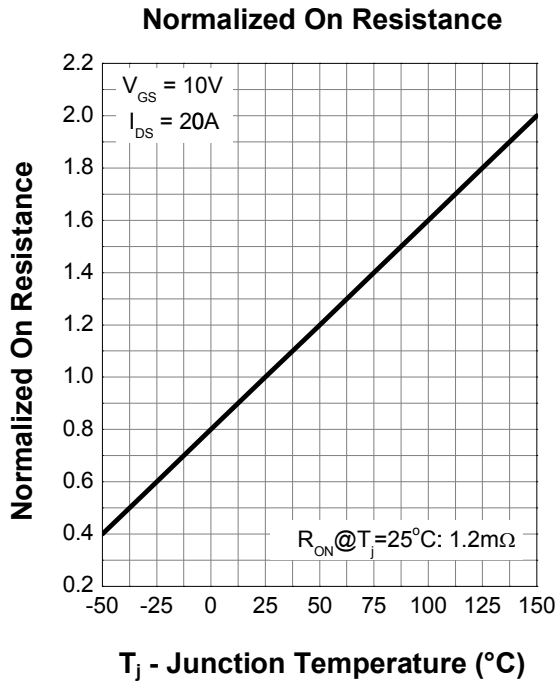
Transfer Characteristics



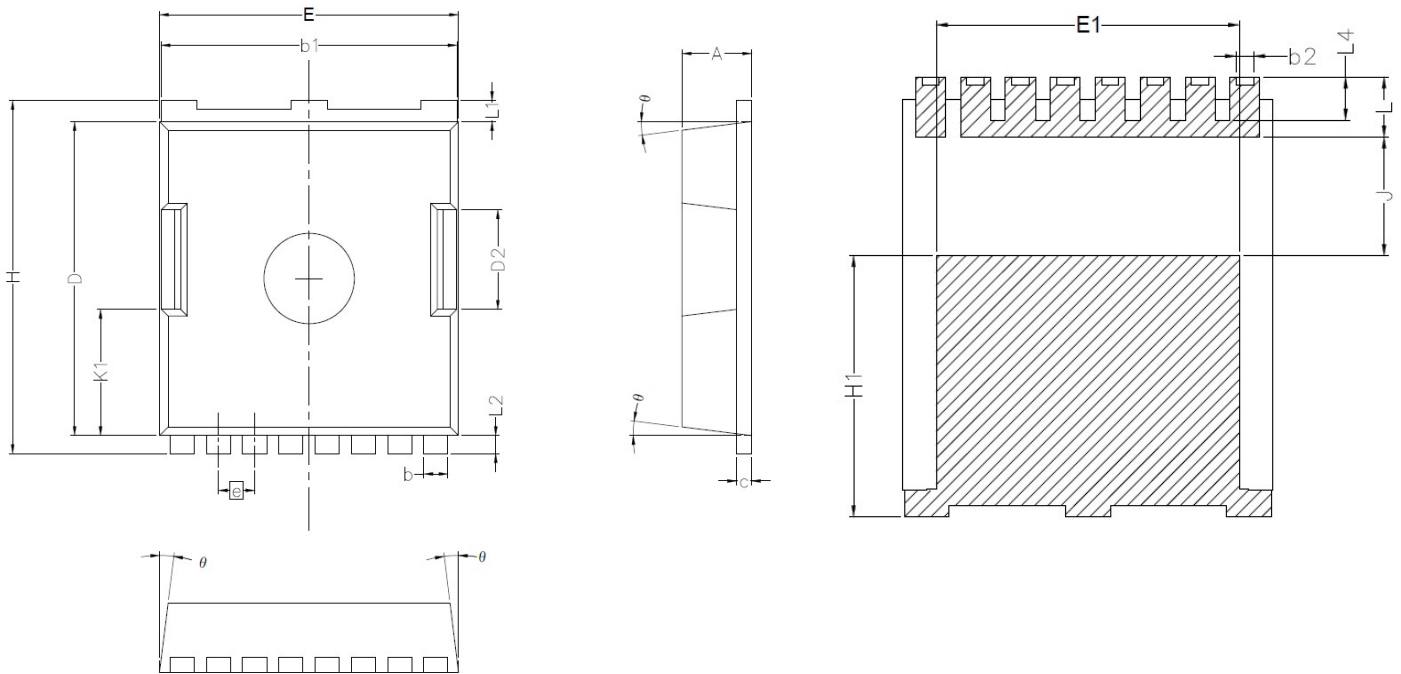
Normalized Threshold Voltage



Typical Characteristics (Cont.)



Package Information : TOLL-8L



Symbol	Dimensions In Millimeters	
	MIN.	MAX.
A	2.20	2.40
b	0.90	0.90
b1	9.70	9.90
b2	0.42	0.50
c	0.40	0.60
D	10.28	10.58
D2	3.10	3.50
E	9.70	10.10
E1	7.90	8.30
e	1.20BSC	
H	11.48	11.88
H1	6.75	7.15
N	8	
J	3.00	3.30
K1	3.98	4.38
L	1.40	1.80
L1	0.60	0.80
L2	0.50	0.70
L4	1.00	1.30
θ	4°	10°